

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	356	semiconductor and optoelectronic and ((encapsul\$5 or resin) with (transparent or translucent))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/27 14:10
S9	270	semiconductor and ((base or frame or substrate) same (groove with adhesion))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/27 14:10
L2	221	semiconductor and optoelectronic and ((encapsul\$6 or resin) with (transparent or translucent)) and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/27 14:11
S3	179	semiconductor and optoelectronic and ((encapsul\$5 or resin) with (transparent or translucent)) and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/27 14:11
L3	2635	(257/432-434).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/27 14:22
L4	864	(257/432-434).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/27 14:24
L5	193	(257/432-434).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and ((encapsul\$5 or resin) with (transparent or translucent))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/27 14:26
L6	3008	(257/678 or 257/680).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/27 14:26
L7	84	(257/678 or 257/680).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and ((encapsul\$5 or resin) with (transparent or translucent))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/27 14:27

L8	10	(257/796).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and ((encapsul\$5 or resin) with (transparent or translucent))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/27 14:27
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